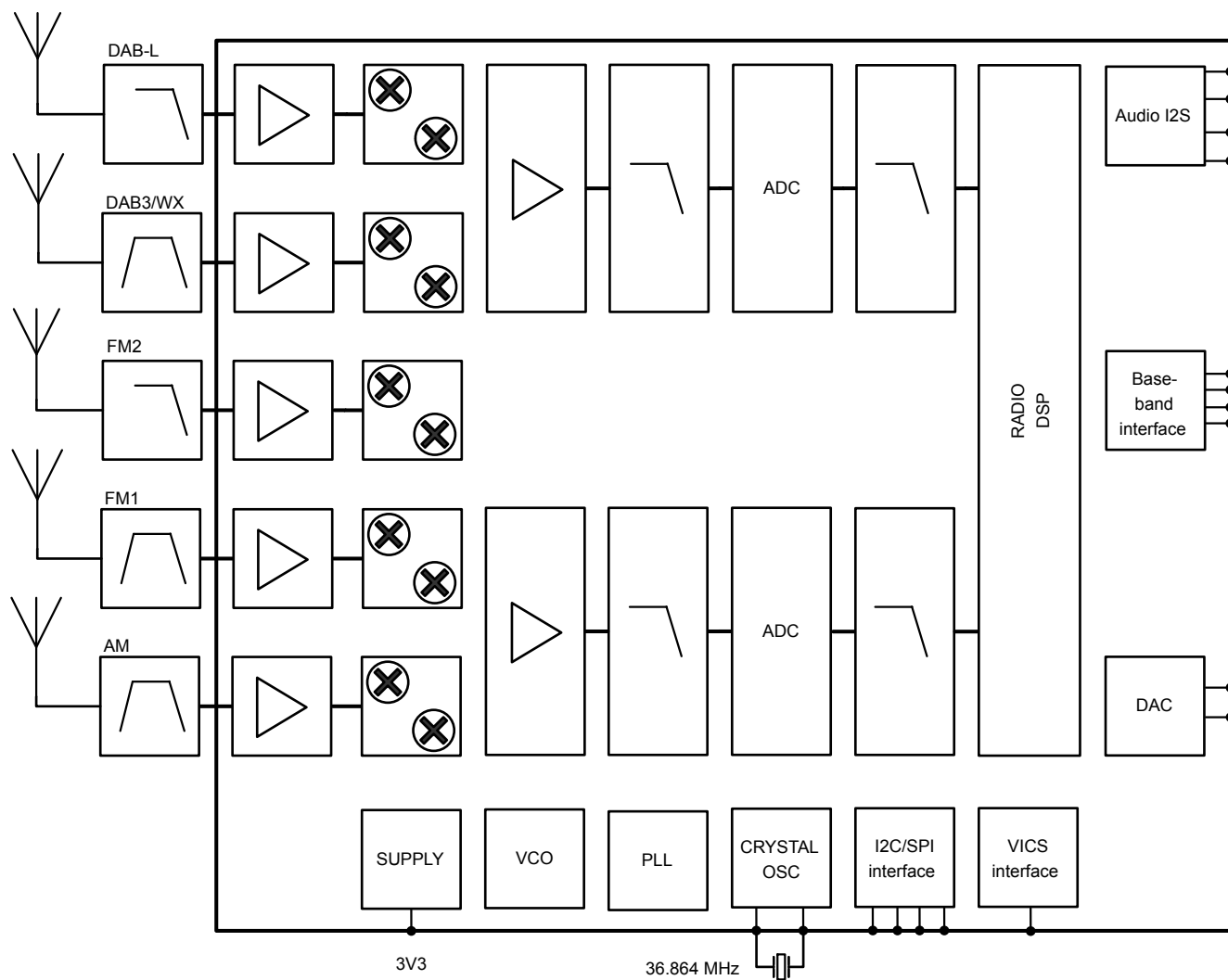


1 Block diagram

Figure 1. Block diagram



2 Electrical specification

2.1 Absolute maximum ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Test condition	Min	Typ	Max	Units
V _{CC}	Abs. supply voltage	-	-0.5	-	3.6	V
T _{stg}	Storage temperature	-	-55	-	150	°C
V _{ESD}	ESD absolute minimum withstand voltage	Human Body model	> ±2000 ⁽¹⁾			V
		Charged device model	> ±500 ⁽²⁾			
		Charged device model, corner pins	> ±750			
-	Max. input current at any pin (latch-up characteristic)	I _{INMAX}	±100			mA

1. $|\pm 1000|$ on AM_IN pin

2. $|\pm 400|$ on AM_IN pin

2.2 Thermal data

Table 2. Thermal data

Symbol	Parameter	Test Condition	Value	Units
$R_{th\ j-amb}$	Thermal Resistance junction-to-ambient	Multilayer 2s2p as per JEDEC JESD51-7	27	°C / W
		Thermally optimized multilayer 2s2p board	22	

2.3 General key parameters

Table 3. General key parameters

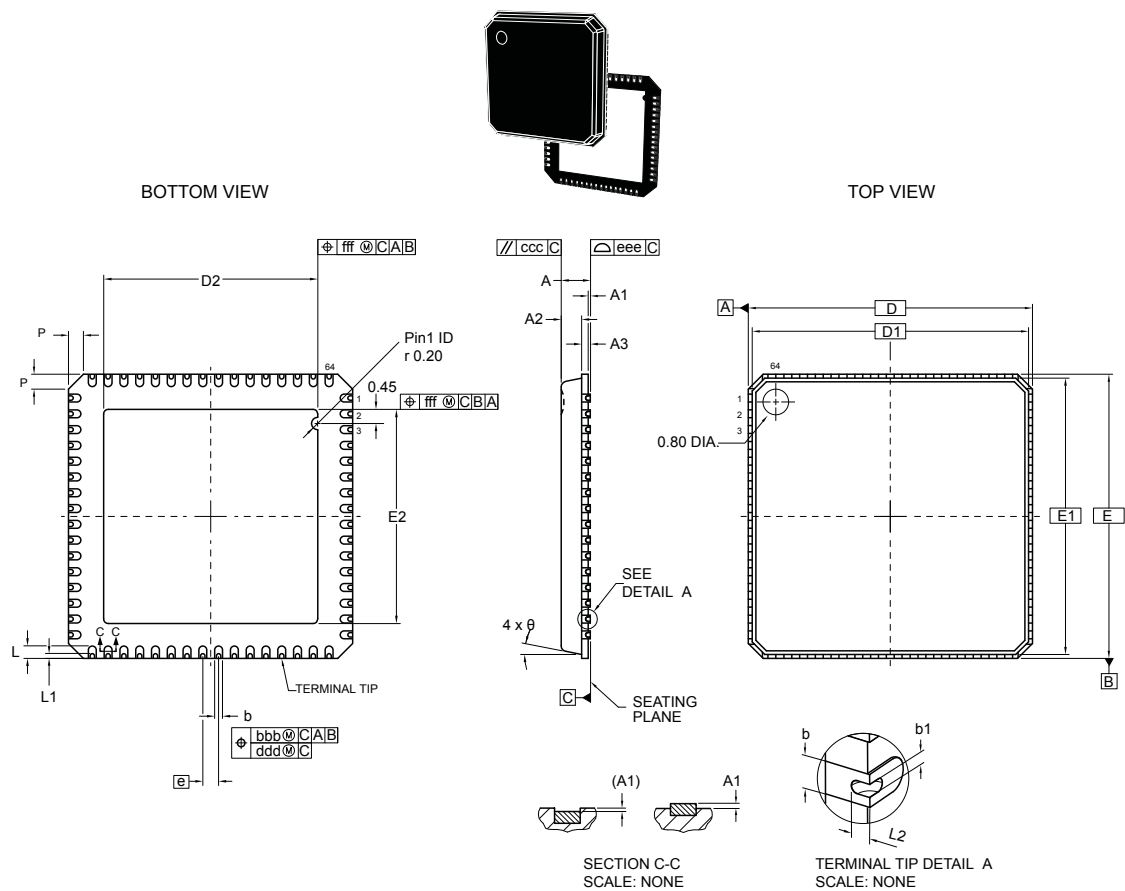
Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{CC}	3.3 V supply voltage		3.15	3.3	3.45	V
I_{CC}	Supply current	Two active RF channels, $V_{CC} = 3.45$ V	-	-	519	mA
		Two active RF channels, JESD204b interface activated (10 pF load), $V_{CC} = 3.45$ V	-	-	600	
T_{amb}	Ambient Temperature Range	-	-40	-	85	°C
T_{j_oper}	Operative Junction Temp	-	-	-	125	°C
P_{diss}	Dissipated power	Two active RF channels, $R_{ext} = 9$ Ohm, I2S baseband interface activated	-	-	1.5	W
		Two active RF channels, $R_{ext} = 7.5$ Ohm, JESD204b interface activated	-	-	1.7	

3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

3.1 VFQFPN-64 (9x9x1.0mm) package information

Figure 2. VFQFPN-64 (9x9x1.0 mm) package outline



8511068_B_A02G

GAPGPS03460

Table 4. VFQFPN-64 (9x9x1.0 mm) package mechanical data

Ref.	Dimensions in mm		
	Min.	Typ.	Max.
Θ	-	-	14
A	-	-	1.0
A1	0.00	-	0.05
A2	0.55	-	0.80
A3	0.20 REF		
b ⁽¹⁾	0.18	0.25	0.30

Ref.	Dimensions in mm		
	Min.	Typ.	Max.
b1	-	0.15	-
D	9.00 BSC		
D1 ⁽²⁾	8.75 BSC		
D2	-	6.70	-
e	0.50 BSC		
E	9.00 BSC		
E1 ⁽²⁾	8.75 BSC		
E2	-	6.70	-
L	0.30	-	0.50
L1	0.15 REF		
L2	-	0.10	-
P	-	-	0.60
Tolerance of form and position			
aaa	0.15		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

1. Maximum allowable burr is 0.076 mm in all directions.

2. D1 and E1 are Maximum plastic body size dimensions including mold mismatch. Dimensions D1 and E1 do not include mold flash or protrusions. Allowable mold flash or protrusions is "0.25 mm (0.0098 inch)" per side.

Note: The package is compliant to IPC/JEDEC J-STD-020D June 2007 standard Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices, MSL Level 3.

Revision history

Table 5. Document revision history

Date	Version	Changes
16-Dec-2014	1	Initial release.
04-Jun-2018	2	Fully revised.
25-Nov-2019	3	Updated Figure 1. Block diagram.

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